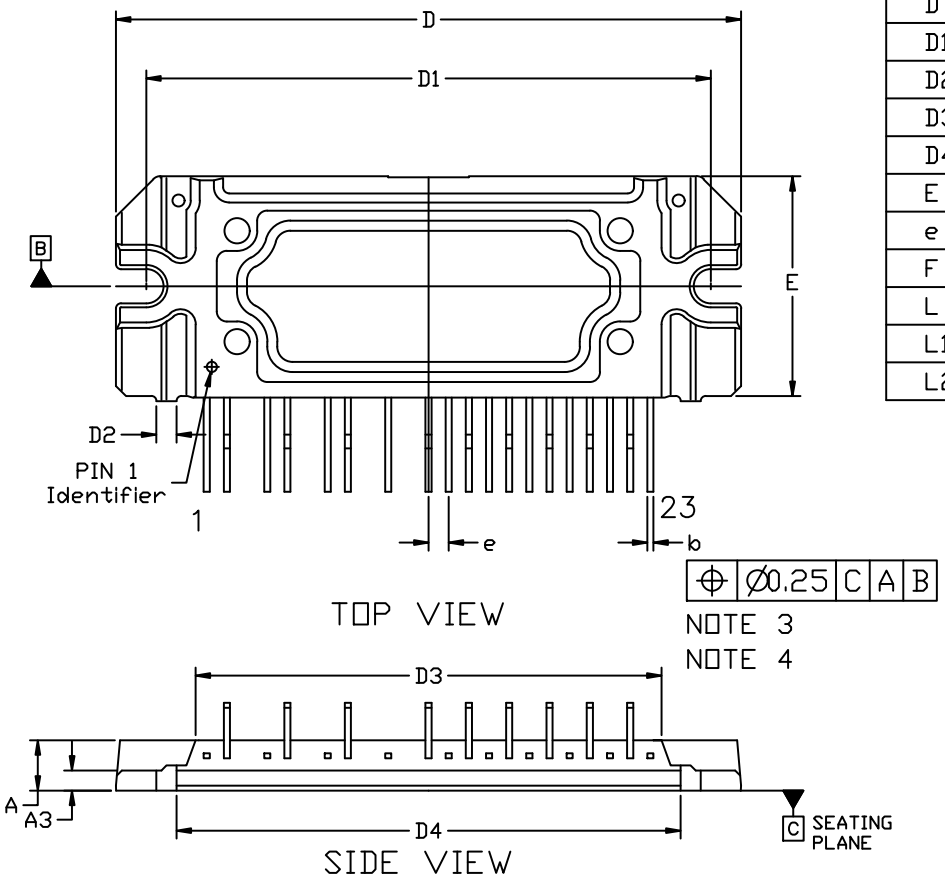
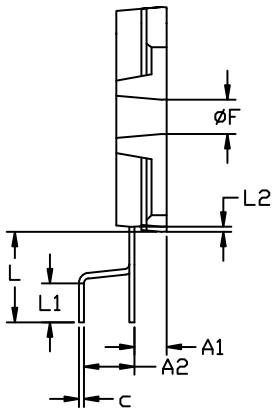
SIP23, 62x21.8 FP−4
CASE 127FC
ISSUE O

DATE 07 JAN 2019

NOTES:
1. DIMENSIONING AND TOLERANCING PER. ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b and c APPLY TO THE PLATED LEADS AND ARE MEASURED BETWEEN 1.00 AND 2.00 FROM THE LEAD TIP.
4. POSITION OF THE LEAD IS DETERMINED AT THE ROOT OF THE LEAD WHERE IT EXITS THE PACKAGE BODY.
5. PIN 1 IDENTIFICATION IS A MIRRORED SURFACE INDENT.
6. MISSING PINS ARE 3,6,9 and 11.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	4.5	5.0	5.5
A1	2.7	3.2	3.7
A2	4.5	5.0	5.5
A3	1.5	2.0	2.5
b	0.55	0.6	0.8
c	0.45	0.5	0.7
D	61.5	62.0	62.5
D1	55.5	56.0	56.5
D2	1.5	2.0	2.5
D3	45.7	46.2	46.7
D4	49.5	50.0	50.5
E	21.3	21.8	22.3
e	2.0 REF		
F	2.9	3.4	3.9
L	8.5	9.0	9.5
L1	3.8	4.3	4.8
L2	0.0	0.5	1.0





GENERIC MARKING DIAGRAM*

XXXX = Specific Device Code
ZZZ = Assembly Lot Code
AT = Assembly & Test Location
Y = Year
WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

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